## MAX14589E/MAX14594E

## High-Density, $\pm 5 V$ Capable DPDT Analog Switches

## General Description

The MAX14589E/MAX14594E high-density, double-pole/ double-throw (DPDT) analog switches feature Beyond-the-Rails ${ }^{\top M}$ capability that allows signals from -5.5 V to +5.5 V to pass without distortion even when the power supply is below the signal range. The low R R ( $0.2 \Omega$ ) makes the devices ideal for low-distortion switching, such as audio.
The MAX14594E has internal shunt switches that discharge the audio amplifier AC-coupling capacitance at the normally open (NO1 and NO2) terminals. This feature reduces click-and-pop sounds that occur when switching audio signals between precharged points.
The switches are fully specified to operate from a single +1.6 V to +5.5 V power supply. Because of the low supply current requirement, $\mathrm{V}_{\text {CCEN }}$ can be provided by a GPIO. When the power is not applied, switches go to a highimpedance mode and all analog signal ports can withstand signals within the analog signal range. The devices control the switches with a control bit, CB.

The MAX14589E/MAX14594E are available in a 1.2mm x $1.2 \mathrm{~mm}, 0.4 \mathrm{~mm}$ pitch, 9 -bump wafer-level package (WLP), and operate over the $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ extended temperature range.

Applications
Smartphones
Tablets
Portable Audio/Video Equipment
Portable Navigation Devices

Benefits and Features

\author{

- Distortion-Free Beyond-the-Rails Signaling <br> $\diamond$ Negative Audio and Video Signal Capable <br> $\diamond-5.5 \mathrm{~V}$ to +5.5 V Analog Signal Range Independent from $V_{\text {CCEN }}$ <br> $\diamond$ On-Resistance $0.2 \Omega$ (typ) <br> $\diamond+1.6 \mathrm{~V}$ to +5.5 V Single-Supply Range <br> $\diamond$ Click-and-Pop Suppression <br> - Smooth Switch Transition <br> $\triangleleft$ Break-Before-Make Operation <br> - Low Supply Current 30رA (typ) at 1.6V <br> $\diamond$ Can be Powered by a GPIO <br> $\diamond$ High-Impedance Mode When Vccen Not Applied <br> - ESD Protection on COM <br> $\diamond \pm 15 k V$ Human Body Model <br> $\diamond \pm 10 k V$ IEC 61000-4-2 Air Gap <br> $\diamond \pm 8 k V$ IEC 61000-4-2 Contact <br> - ESD Protection on NC_ and NO_ $\diamond \pm 15 k V$ Human Body Model <br> - Small Board Space <br> $\diamond$ 9-Bump WLP (1.2mm x 1.2mm) Package <br> $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ Operating Temperature Range
}

Ordering Information/Selector Guide appears at end of data sheet.

For related parts and recommended products to use with this part, refer to www.maximintegrated.com/MAX14589E.related.

High-Density, $\pm 5 V$ Capable DPDT Analog Switches
Typical Application Circuits/Functional Diagrams


## MAX14589E/MAX14594E

## High-Density, $\pm 5 V$ Capable DPDT Analog Switches

## ABSOLUTE MAXIMUM RATINGS

(All Voltages Referenced to GND.)


Continuous Power Dissipation $\left(\mathrm{T}_{\mathrm{A}}=+70^{\circ} \mathrm{C}\right)$
WLP (derate $12 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ )...................... 963.8 mW
Operating Temperature Range .......................... $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$
Junction Temperature ..................................................... $+150^{\circ} \mathrm{C}$
Storage Temperature Range........................ $-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$
Soldering Temperature (reflow) ...................................... $+260^{\circ} \mathrm{C}$

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## PACKAGE THERMAL CHARACTERISTICS (Note 1)

WLP
Junction-to-Ambient Thermal Resistance ( $\theta_{\mathrm{JA}}$ ) .......... $83^{\circ} \mathrm{C} / \mathrm{W}$
Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

## ELECTRICAL CHARACTERISTICS

$\left(\mathrm{V}_{\text {CCEN }}=+1.6 \mathrm{~V}\right.$ to $+5.5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at $\mathrm{V}_{\mathrm{CCEN}}=+2.5 \mathrm{~V}$ and $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$. $)$ (Note 2)

| PARAMETER | SYMBOL | CONDITIONS |  | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| POWER SUPPLY |  |  |  |  |  |  |  |
| Power-Supply Range | $\mathrm{V}_{\text {CCEN }}$ |  |  | 1.6 |  | 5.5 | V |
| PSRR |  | $\mathrm{R}_{\text {COM }}=32 \Omega, \mathrm{f}=20 \mathrm{kHz}$ |  | 80 |  |  | dB |
| $\mathrm{V}_{\text {CCEN }}$ Supply Current | ${ }^{\text {cc }}$ | $\mathrm{V}_{\text {CCEN }}=+1.60 \mathrm{~V}, \mathrm{~V}_{\text {CB }}=0 \mathrm{~V}$ or $\mathrm{V}_{\text {CCEN }}$ |  |  | 30 | 50 | $\mu \mathrm{A}$ |
|  |  | $\mathrm{V}_{\mathrm{CCEN}}=+4.2 \mathrm{~V}, \mathrm{~V}_{\mathrm{CB}}=0 \mathrm{~V}$ or $\mathrm{V}_{\text {CCEN }}$ |  |  | 35 | 60 |  |
| ANALOG SWITCH |  |  |  |  |  |  |  |
| Analog Signal Range (Note 3) | $\mathrm{V}_{\text {NC_ }}$, <br> $\mathrm{V}_{\text {NO_ }}$, <br> $\mathrm{V}_{\mathrm{COM}}$ | $\mathrm{V}_{\text {CCEN }}>1.6 \mathrm{~V}$ |  | -5.5 |  | +5.5 | V |
|  |  | $\mathrm{V}_{\text {CCEN }}<1.6 \mathrm{~V}, \mathrm{R}_{\mathrm{S}}=50 \Omega$ |  | -5.5 |  | +5.5 |  |
| On-Resistance | RON | $\begin{aligned} & \mathrm{V}_{\text {COM }}=0 \mathrm{~V}, \\ & \mathrm{I}_{\mathrm{COM}}^{-} \\ & =100 \mathrm{~mA}(\text { Note } 4) \end{aligned}$ | $\mathrm{V}_{\text {CCEN }}=2.5 \mathrm{~V}$ |  | 0.2 | 0.38 | $\Omega$ |
|  |  |  | $\mathrm{V}_{\text {CCEN }}=1.8 \mathrm{~V}$ |  | 0.25 | 0.43 |  |
| On-Resistance Match Between Channels | $\Delta \mathrm{R}_{\mathrm{ON}(\mathrm{NC)}}$ | $\mathrm{V}_{\text {CCEN }}=2.5 \mathrm{~V}, \mathrm{~V}_{\mathrm{NC}_{-}}=0 \mathrm{~V}, \mathrm{I}_{\mathrm{COM}}=100 \mathrm{~mA},$ between same NC_ and NO_ channel (Note 5) |  |  | 0.005 | 0.05 | $\Omega$ |
| On-Resistance Flatness | RFLAt(ON) | $\begin{array}{\|l\|} \hline \mathrm{V}_{\text {CCEN }}=2.5 \mathrm{~V}, \mathrm{I}_{\text {COM }}=100 \mathrm{~mA}, \\ \mathrm{~V}_{\text {COM }}=-5.5 \mathrm{~V} \text { to }+5.5 \mathrm{~V}(\text { Notes } 6,7) \\ \hline \end{array}$ |  |  | 0.001 | 0.01 | $\Omega$ |
| Shunt Switch Resistance | $\mathrm{R}_{\text {SHUNT }}$ | $\mathrm{I}_{\text {COM_ }}=1 \mathrm{~mA}, \mathrm{MAX14594E}$ |  |  | 500 | 1000 | $\Omega$ |
| NC_ or NO_ <br> Off-Leakage Current | ${ }^{\text {In }}$ NC_(OFF), <br> INO_(OFF) | $\begin{aligned} & \hline \mathrm{V}_{\text {CCEN }}=2.5 \mathrm{~V} \text {; open switch; } \\ & \mathrm{V}_{\text {NO_ }} \text { or } \mathrm{V}_{\text {NC }}=-5.5 \mathrm{~V},+5.5 \mathrm{~V} \text {; } \\ & \mathrm{V}_{\text {COM_ }}=+5.5 \mathrm{~V},-5.5 \mathrm{~V} \text {, unconnected } \\ & \hline \end{aligned}$ |  | -400 |  | +400 | nA |
|  |  | $\mathrm{V}_{\text {CCEN }}=0 \mathrm{~V}$; $\mathrm{V}_{\text {NO_ }}$ or $\mathrm{V}_{\text {NC_ }}=0 \mathrm{~V},+5.5 \mathrm{~V}$; <br> $\mathrm{V}_{\mathrm{COM}}=+5.5 \mathrm{~V}$, 0 V , unconnected |  | -400 |  | +400 |  |
| COM_ Off-Leakage Current | ICOM_(OFF) | $\mathrm{V}_{\text {CCEN }}=0 \mathrm{~V}$; $\mathrm{V}_{\text {COM }}=+5.5 \mathrm{~V}$, OV; <br> $\mathrm{V}_{\mathrm{NO}_{-}}$or $\mathrm{V}_{\mathrm{NC}_{-}}=0 \mathrm{~V},+5.5 \mathrm{~V}$, unconnected |  | -400 |  | +400 | nA |

## High-Density, $\pm 5 V$ Capable DPDT Analog Switches

## ELECTRICAL CHARACTERISTICS (continued)

$\left(\mathrm{V}_{\mathrm{CC}}=+1.6 \mathrm{~V}\right.$ to $+5.5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at $\mathrm{V}_{\mathrm{CC}}=+2.5 \mathrm{~V}$ and $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$.) (Note 2)

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| COM_ On-Leakage Current | ICOM_(ON) | $\mathrm{V}_{\text {CCEN }}=2.5 \mathrm{~V}$; switch closed; <br> $\mathrm{V}_{\text {COM }}=+5.5 \mathrm{~V},-5.5 \mathrm{~V}$; <br> $\mathrm{V}_{\mathrm{NO}_{-}}$or $\mathrm{V}_{\mathrm{NC}_{-}}=+5.5 \mathrm{~V},-5.5 \mathrm{~V}$, unconnected | -400 |  | +400 | nA |
| DYNAMIC TIMING |  |  |  |  |  |  |
| Turn-On Time | ton | $\mathrm{V}_{\text {NO_ }}$ or $\mathrm{V}_{\text {NC_ }}=0 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=50 \Omega$, Figure 1 a (Note 6) |  | 5 | 10 | ms |
| Turn-Off Time | toff | $\mathrm{V}_{\text {NO_ }}$ or $\mathrm{V}_{\text {NC_ }}=0 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=50 \Omega$, Figure 1a (Note 6) |  | 1 | 2.25 | ms |
| Break-Before-Make Time | ${ }_{\text {tBBM }}$ | $R_{L}=50 \Omega, V_{C C E N}=3.3 \mathrm{~V}$, time for both NC_/NO_ switches are open during transition, Figure 1b (Note 6) | 0 | 5 | 10 | ms |
| AUDIO PERFORMANCE |  |  |  |  |  |  |
| Total Harmonic Distortion Plus Noise | THD+N | $\begin{aligned} & f=20 \mathrm{~Hz} \text { to } 20 \mathrm{kHz}, \mathrm{~V}_{C O M}=0.5 \mathrm{~V}_{\mathrm{P}-\mathrm{P}}, \\ & R_{S}=R_{L}=50 \Omega, \mathrm{DC} \text { bias }=0 \mathrm{~V} \end{aligned}$ |  | 0.001 |  | \% |
| Off-Isolation | VISO | $R_{S}=R_{L}=50 \Omega, V_{C O M}=0.5 \mathrm{~V}_{\text {P-P }}$, $\mathrm{f}=100 \mathrm{kHz}, \mathrm{V}_{\mathrm{CCEN}}=0 \mathrm{~V}$, DC bias $=0.25 \mathrm{~V}$, Figure 2 |  | -60 |  | dB |
| Crosstalk | $V_{C T}$ | $\begin{aligned} & R_{S}=R_{L}=50 \Omega, V_{C O M}=0.5 V_{P-P}, \\ & f=100 \mathrm{kHz}, \text { Figure } 2 \text { (Note 8) } \end{aligned}$ |  | -80 |  | dB |
| -3dB Bandwidth (Note 9) | BW | $\mathrm{R}_{S}=\mathrm{R}_{\mathrm{L}}=50 \Omega, \mathrm{~V}_{\text {NO_/ }} \mathrm{NC}, \mathrm{V}_{\text {COM }}<2 \mathrm{~V}_{\text {P-P }}$ |  | 200 |  | MHz |
| NC_ or NO_ Off-Capacitance | $\begin{aligned} & \mathrm{C}_{\text {NC_(OFF) }} \\ & \mathrm{C}_{\mathrm{NO} \text { _( }} \text { OFF) } \end{aligned}$ | $\mathrm{V}_{\text {NC_ } / \mathrm{NO}_{-}}=0.5 \mathrm{~V}_{\text {P-P, }} \mathrm{f}=1 \mathrm{MHz}$ |  | 25 |  | pF |
| COM_ On-Capacitance | CCOM_(ON) | $\mathrm{V}_{\text {NC_ }} \mathrm{NO}_{-}=0.5 \mathrm{~V}_{\text {P-P }}, \mathrm{f}=1 \mathrm{MHz}$ |  | 50 |  | pF |
| DIGITAL I/O (CB) |  |  |  |  |  |  |
| Input Logic-High Voltage | $\mathrm{V}_{\mathrm{IH}}$ |  | 1.4 |  |  | V |
| Input Logic-Low Voltage | $\mathrm{V}_{\text {IL }}$ |  |  |  | 0.4 | V |
| Input Leakage Current | IIN | $\mathrm{V}_{\mathrm{CB}}=0 \mathrm{~V}$ or $\mathrm{V}_{\text {CCEN }}$ | -1 |  | +1 | $\mu \mathrm{A}$ |
| ESD PROTECTION |  |  |  |  |  |  |
| COM1, COM2 |  | Human Body Model |  | $\pm 15$ |  | kV |
|  |  | IEC 61000-4-2 Air-Gap Discharge |  | $\pm 10$ |  |  |
|  |  | IEC 61000-4-2 Contact Discharge |  | $\pm 8$ |  |  |
| NO_, NC_ |  | Human Body Model |  | $\pm 15$ |  | kV |
| All Other Pins |  | Human Body Model |  | $\pm 2$ |  | kV |

Note 2: All specifications are $100 \%$ production tested at $T_{A}=+25^{\circ} \mathrm{C}$, unless otherwise noted. Specifications are over $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ and are guaranteed by design.
Note 3: Full analog voltage range supported for signal frequencies less than 50 kHz applied to all signal pins.
Note 4: The same limits apply for $\mathrm{V}_{\text {COM }}=-5.5 \mathrm{~V}$ to +5.5 V and are guaranteed by design.
Note 5: $\Delta \mathrm{R}_{\mathrm{ON}(\mathrm{MAX})}=\mathrm{IR}_{\mathrm{ON}(\mathrm{CH} 1)}-\mathrm{R}_{\mathrm{ON}(\mathrm{CH} 2)}{ }^{1}$.
Note 6: Guaranteed by design; not production tested.
Note 7: Flatness is defined as the difference between the maximum and minimum value of on-resistance, as measured over specified analog signal ranges.
Note 8: Between two switches.
Note 9: Full bandwidth supported for signal amplitudes less than 2 V peak-to-peak applied to all signal pins.

## High-Density, +5V Capable DPDT Analog Switches

Timing Diagrams


Figure 1a. Switching Time


Figure 1b. Break-Before-Make Interval

*FOR CROSSTALK THIS PIN IS NO2. NC2 AND COM2 ARE OPEN.
OFF-ISOLATION IS MEASURED BETWEEN COM_ AND "OFF" NO_ OR NC_ TERMINAL ON EACH SWITCH. OFF-ISOLATION $=2010 \frac{V_{\text {OUT }}}{V_{\text {IN }}}$ ON-LOSS IS MEASURED BETWEEN COM_ AND "ON" NO_OR NC_ TERMINAL ON EACH SWITCH. ON-LOSS $=20100 \frac{V_{0 U T}}{V_{I N}}$ CROSSTALK IS MEASURED FROM ONE CHANNEL TO THE OTHER CHANNEL. CROSSTALK $=20100 \frac{V_{\text {OUT }}}{V_{\text {IN }}}$

Figure 2. On-Loss, Off-Isolation, and Crosstalk

MAX14589E/MAX14594E

## High-Density, $\pm 5 V$ Capable DPDT Analog Switches

Typical Operating Characteristics
$\left(\mathrm{V}_{\text {CCEN }}=+2.5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, unless otherwise noted. $)$


COM_ LEAKAGE CURRENT
vs. TEMPERATURE


## High-Density, $\pm 5 V$ Capable DPDT Analog Switches

Typical Operating Characteristics (continued)

*Note: Signals with frequencies greater than 50 kHz are supported for amplitudes up to $2 V_{P-p}$. Full analog voltage range supported for signal frequencies less than 50 kHz applied to any signal pin.

MAX14589E/MAX14594E

## High-Density, $\pm 5 V$ Capable DPDT Analog Switches

Bump Configuration


Bump Description

| BUMP | NAME | FUNCTION |
| :---: | :---: | :--- |
| A1 | NC1 | Normally Closed Terminal for Switch 1 |
| A2 | CB | Digital Control Input. Drive CB low to connect COM_ to NC_. Drive CB high to connect COM_ to NO_. |
| A3 | NC2 | Normally Closed Terminal for Switch 2 |
| B1 | COM1 | Common Terminal for Switch 1 |
| B2 | GND | Ground |
| B3 | COM2 | Common Terminal for Switch 2 |
| C1 | NO1 | Normally Open Terminal for Switch 1 |
| C2 | VCCEN | Positive Supply Voltage Input. Bypass $V_{\text {CCEN }}$ to GND with a 0.1 1 F capacitor as close as possible to the <br> device. |
| C3 | NO2 | Normally Open Terminal for Switch 2 |

## MAX14589E/MAX14594E

## High-Density, $\pm 5 V$ Capable DPDT Analog Switches

## Detailed Description

The MAX14589E/MAX14594E are low on-resistance and high ESD-protected DPDT switches that operate from a +1.6 V to +5.5 V supply and are designed to multiplex AC-coupled analog signals. These switches feature the low on-resistance ( $\mathrm{R}_{\mathrm{ON}}$ ) necessary for highperformance switching applications. The Beyond-theRails signal capability of the analog channel allows signals below ground, and above $\mathrm{V}_{\text {CCEN }}$, to pass through without distortion.

## Analog Signal Levels

 The devices are bidirectional, allowing NO_, NC_, and COM_ to be configured as either inputs or outputs. The topology of the internal switches allows the signal to drop below ground without the need of an external negative voltage supply. Note: The devices can withstand analog signal levels of -5.5 V to +5.5 V when the device is not powered.Digital Control Input The devices provide a single-bit control logic input, CB. CB controls the switch position, as shown in the Typical Application Circuits/Functional Diagrams.

## Click-and-Pop Suppression <br> (MAX14594E Only)

The $500 \Omega$ shunt resistors automatically discharge any capacitance at both $\mathrm{NO}_{\text {_ }}$ terminals when they are not connected to COM_. This reduces audio click-and-pop


Figure 3. Human Body ESD Test Model
sounds that might occur when switching between capacitively coupled audio sources.
The shunt resistors are controlled by CB. When CB is low, NC_ is connected to COM_, and $\mathrm{NO}_{-}$is connected to the shunt resistors. When CB is high, NO_ is connected to COM_ and the shunt resistors are unconnected.

## Applications Information

Extended ESD Protection
ESD-protection structures are incorporated on all pins to protect against electrostatic discharges up to $\pm 2 \mathrm{kV}$ (HBM) encountered during handling and assembly. COM1 and COM2 are further protected against ESD up to $\pm 15 \mathrm{kV}$ (HBM), $\pm 10 \mathrm{kV}$ (Air-Gap Discharge), and $\pm 8 \mathrm{kV}$ (Contact Discharge) without damage. NO_ and NC_ are further protected against ESD up to $\pm 15 \mathrm{kV}$ (HBM) without damage. The ESD structures withstand high ESD both in normal operation and when the device is powered down. After an ESD event, the devices continue to function without latchup.

ESD Test Conditions
ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test methodology and test results.

Human Body Model
Figure 3 shows the Human Body Model. Figure 4 shows the current waveform it generates when discharged into a low impedance. This model consists of a 100 pF capacitor charged to the ESD voltage of interest that is then discharged into the device through a $1.5 \mathrm{k} \Omega$ resistor.

IEC 61000-4-2 The IEC 61000-4-2 standard covers ESD testing and performance of finished equipment. It does not specifically refer to integrated circuits. The major difference between tests done using the HBM and IEC 61000-4-2 is higher peak current in IEC 61000-4-2, because series resistance is lower in the IEC 61000-4-2 model. Hence, the ESD withstand voltage measured to IEC 61000-4-2 is generally lower than that measured using the HBM. Figure 4 shows the IEC 61000-4-2 model and Figure 5 shows the current waveform for the $\pm 8 \mathrm{kV}$, IEC 61000-4-2, Level 4, ESD Contact-Discharge Method.

## High-Density, $\pm 5 V$ Capable DPDT Analog Switches



Figure 4. IEC 61000-4-2 ESD Test Model

Chip Information
PROCESS: BiCMOS

|  | Ordering Information/ <br> Selector Guide |  |  |
| :---: | :---: | :---: | :---: |
| PART | PIN- <br> PACKAGE | TOP | SHUNT |
| MARK | RESISTOR |  |  |$|$

Note: All devices are specified over the $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ temperature range.
+Denotes a lead(Pb)-free/RoHS-compliant package.
$T=$ Tape and reel.


Figure 5. IEC 61000-4-2 ESD Generator Current Waveform

Package Information
For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "\#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

| PACKAGE <br> TYPE | PACKAGE <br> CODE | OUTLINE <br> NO. | LAND <br> PATTERN NO. |
| :---: | :---: | :---: | :---: |
| 9 WLP | W91B1+7 | $\underline{21-0459}$ | Refer to <br> Application <br> Note 1891 m |

## High-Density, $\pm 5 V$ Capable DPDT Analog Switches

Revision History

| REVISION <br> NUMBER | REVISION <br> DATE | DESCRIPTION | PAGES <br> CHANGED |
| :---: | :---: | :--- | :---: |
| 0 | $6 / 12$ | Initial release | - |
| 1 | $1 / 13$ | Updated Electrical Characteristics table, added note to TOCs | 4,7 |
| 2 | $7 / 14$ | Updated TOC $13,15,16$ | 1,7 |

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